

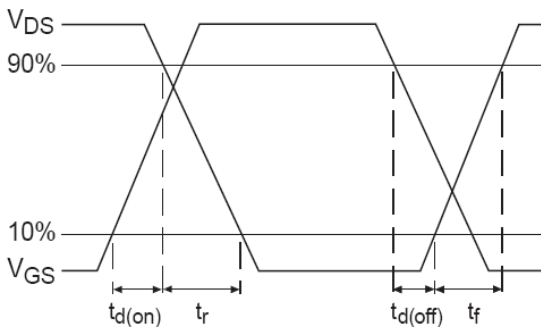
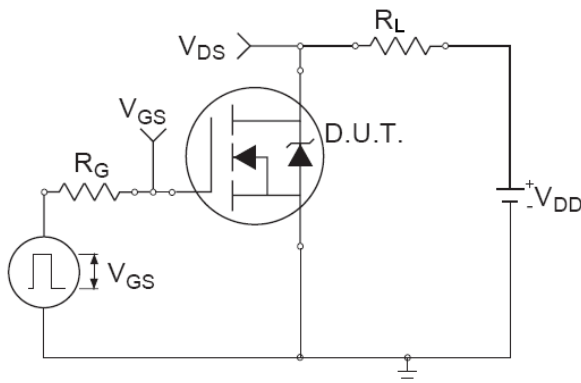
**Features**

- V<sub>DS</sub>=100V/V<sub>GS</sub>=±20V/I<sub>D</sub>=3.5A
- R<sub>DS(ON)</sub>=105mΩ(Max.)@V<sub>GS</sub>=10V
- R<sub>DS(ON)</sub>=175mΩ(Max.)@V<sub>GS</sub>=4.5V
- ESD protect
- Reliable and Rugged
- High Density Cell Design For Ultra Low On-Resistance

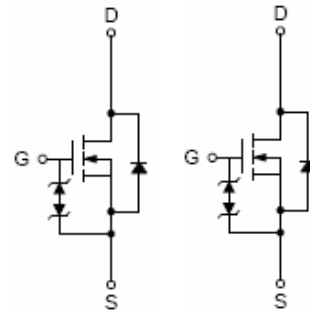
**Applications**

- Synchronous Rectification
- Power Management in Inverter System

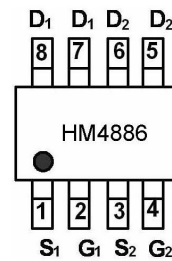
**Switching Time Test Circuit and Waveforms**



**Pin Description**



**Marking and pin Assignment**



SOP-8 top view

**Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
HM4886	HM4886E	SOP-8	-	-	-

**Absolute Maximum Ratings** (T<sub>A</sub>=25°C unless otherwise noted)

Symbol	Parameter	Typical	Unit	
V <sub>DSS</sub>	Drain-Source Voltage	100	V	
V <sub>GSS</sub>	Gate -Source Voltage	±20	V	
I <sub>D</sub> <sup>1</sup>	Continuous Drain Current	T <sub>C</sub> =70°C	2.8	A
			3.5	A
I <sub>DM</sub> <sup>1</sup>	300us Pulsed Drain Current Tested	T <sub>C</sub> =25°C	14	A
I <sub>S</sub> <sup>1</sup>	Diode Continuous Forward Current		3	A
E <sub>AS</sub> <sup>2</sup>	Avalanche Energy, Single Plused(L=0.3mH)		30	mJ
T <sub>J</sub>	Operating Junction Temperature		150	°C
T <sub>STG</sub>	Storage Temperature Range		-55 ~ 150	°C

Note: 1: Surface Mounted on 1in<sup>2</sup> pad area, t ≤ 10sec..

2: UIS tested and pluse width limited by maximum junction temperature 150°C (initial temperature T<sub>J</sub>=25°C).

**Electrical Characteristics** (T<sub>A</sub>=25°C unless otherwise noted)

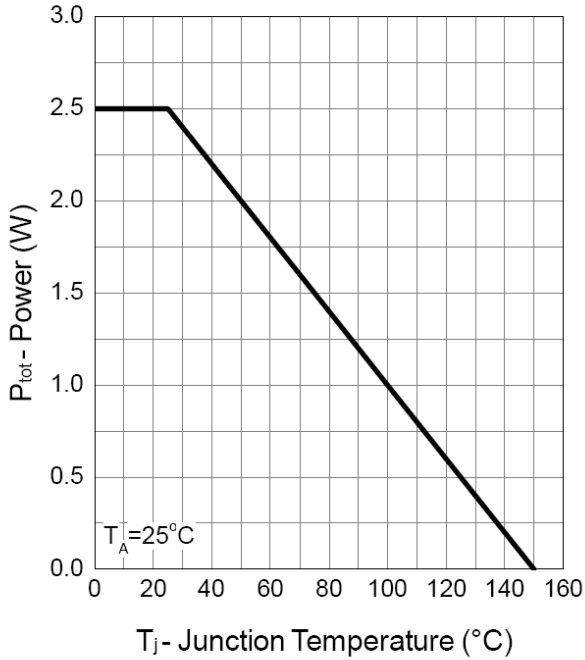
Symbol	Parameter	Test Conditions	Min.	Typ	Max.	Unit
<b>Static Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	100			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-80V, V <sub>GS</sub> =0V			1	uA
		T <sub>J</sub> =85°C			30	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250uA	1.5	2	2.5	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>GS</sub> =±16V, V <sub>DS</sub> =0V			±10	nA
R <sub>DSON</sub> <sup>1</sup>	Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =3.5A		85	105	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =2A		135	175	
<b>Diode Characteristics</b>						
V <sub>SD</sub> <sup>1</sup>	Diode Forward Voltage	I <sub>SD</sub> =3A, V <sub>GS</sub> =0V	0.6	0.8	1.1	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>SD</sub> =3.5A,		44		ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI <sub>SD</sub> /dt=100A/us		80		nC
<b>Dynamic Characteristics<sup>2</sup></b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =30V Frequency=1MHz		940		pF
C <sub>oss</sub>	Output Capacitance			80		
C <sub>rss</sub>	Reverse Transfer Capacitance			50		
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =30V, R <sub>L</sub> =30Ω I <sub>D</sub> =1A, V <sub>GEN</sub> =10V R <sub>G</sub> =6Ω		13	24	ns
t <sub>r</sub>	Turn-On Rise Time			10	19	
t <sub>d(off)</sub>	Turn-Off Delay Time			32	60	
t <sub>f</sub>	Turn-Off Fall Time			16	30	
<b>Gate Charge Characteristics<sup>2</sup></b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =50V, V <sub>GS</sub> =10V I <sub>D</sub> =3.5A		21		nC
Q <sub>gs</sub>	Gate-Source Charge			4.9		
Q <sub>gd</sub>	Gate-Drain Charge			5.8		

Note: 1: Pulse test ; pulse width ≤ 300ns, duty cycle ≤ 2%.

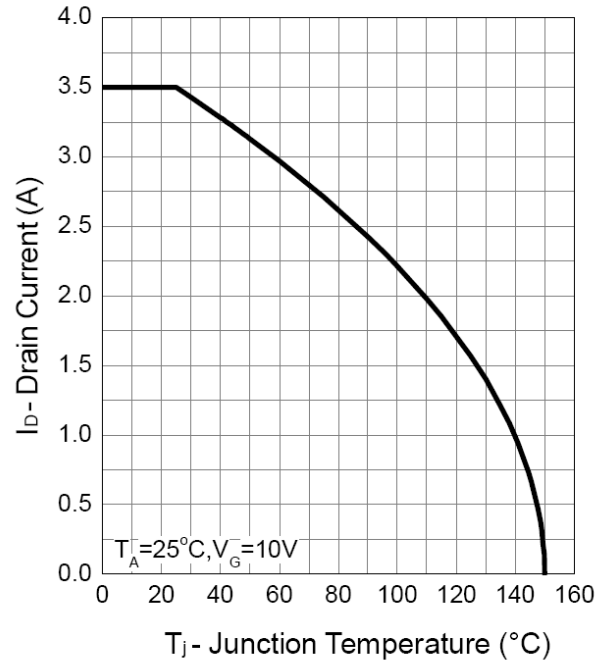
2: Guaranteed by design, not subject to production testing.

Typical Characteristics

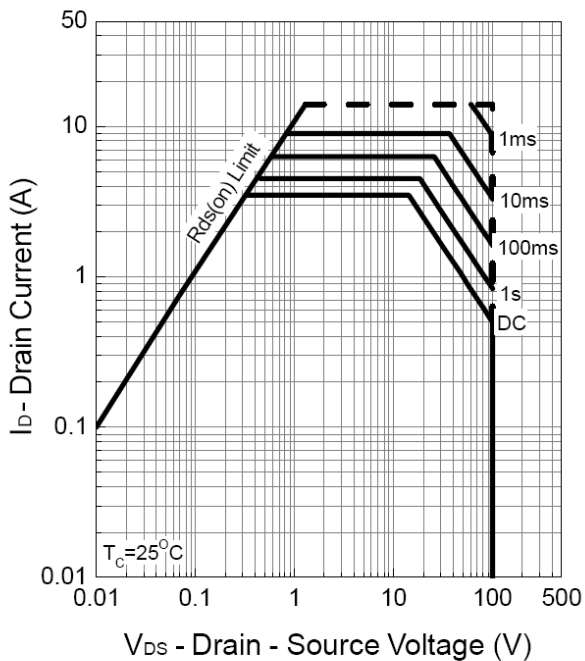
Power Dissipation



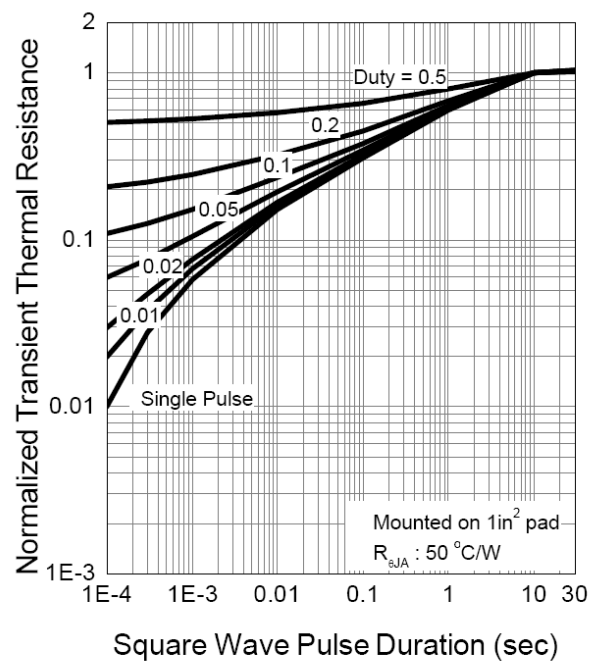
Drain Current



Safe Operation Area

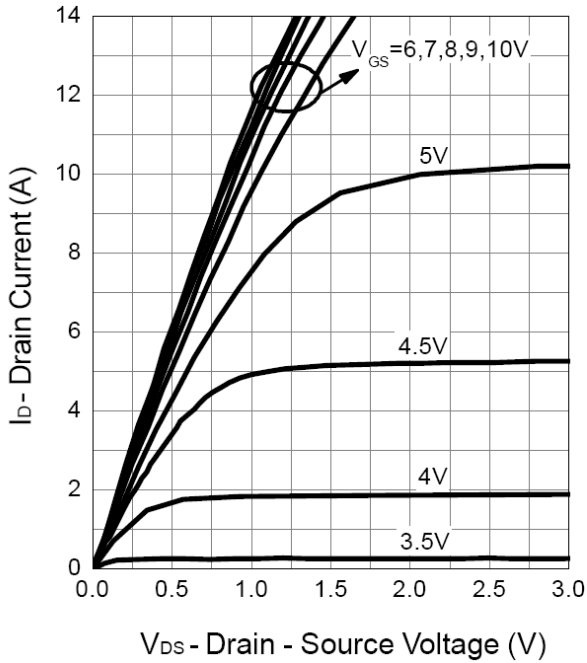


Thermal Transient Impedance

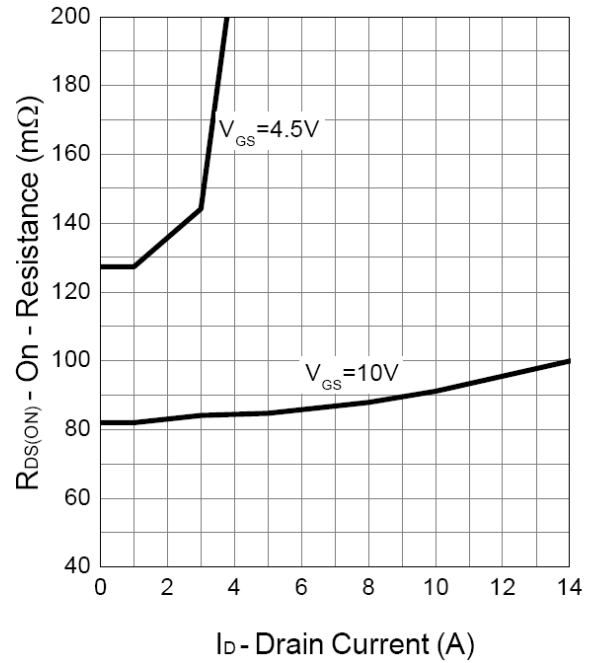


Typical Characteristics (Cont.)

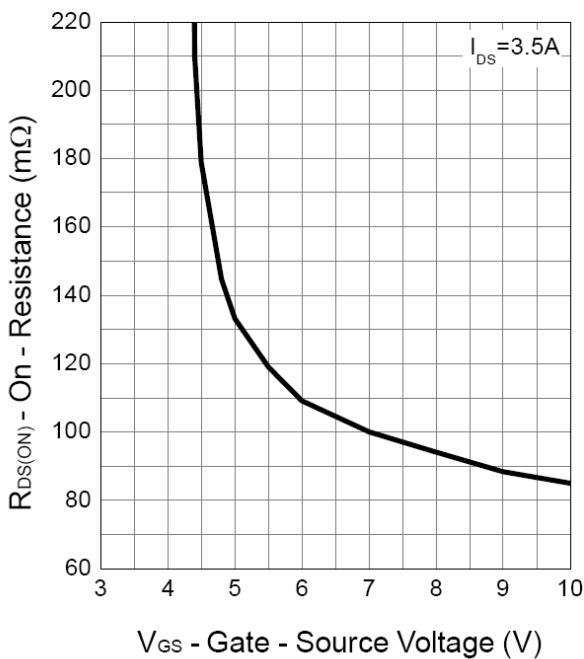
Output Characteristics



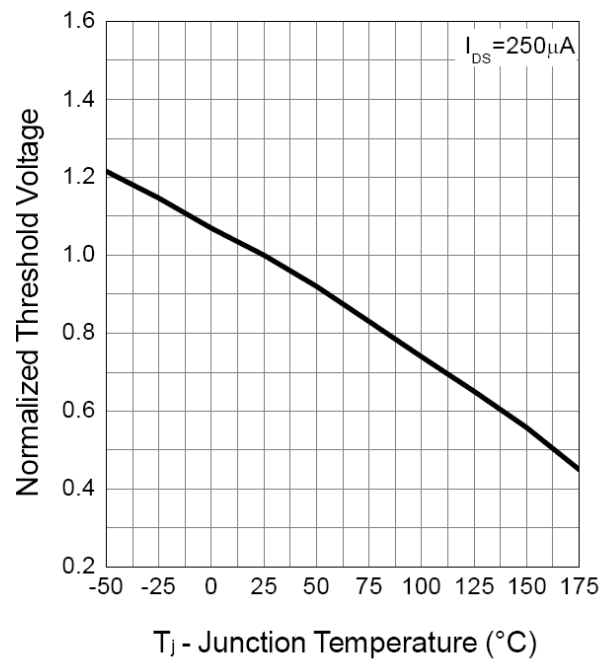
Drain-Source On Resistance



Gate-Source On Resistance

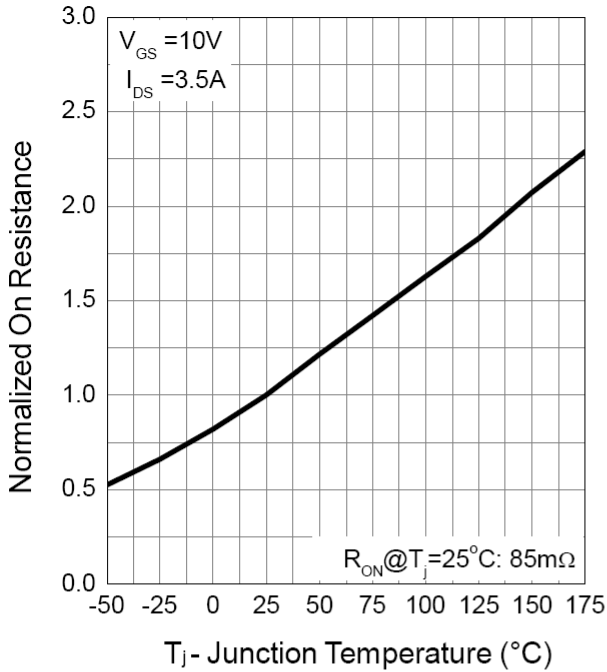


Gate Threshold Voltage

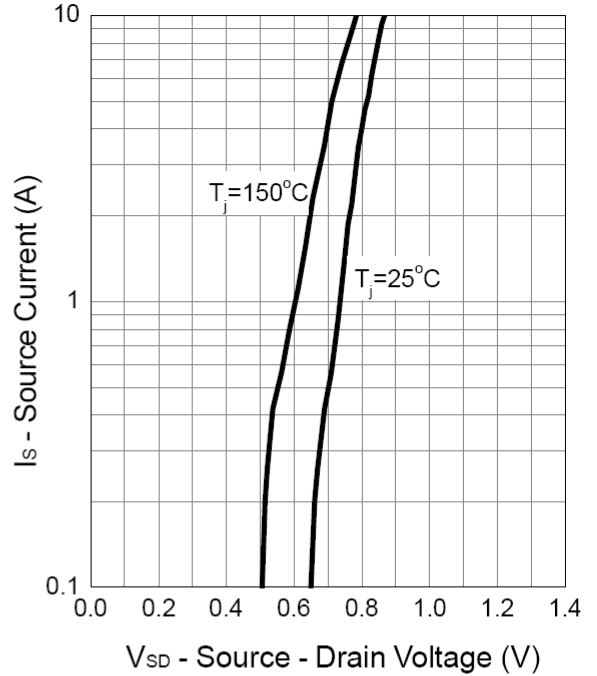


Typical Characteristics (Cont.)

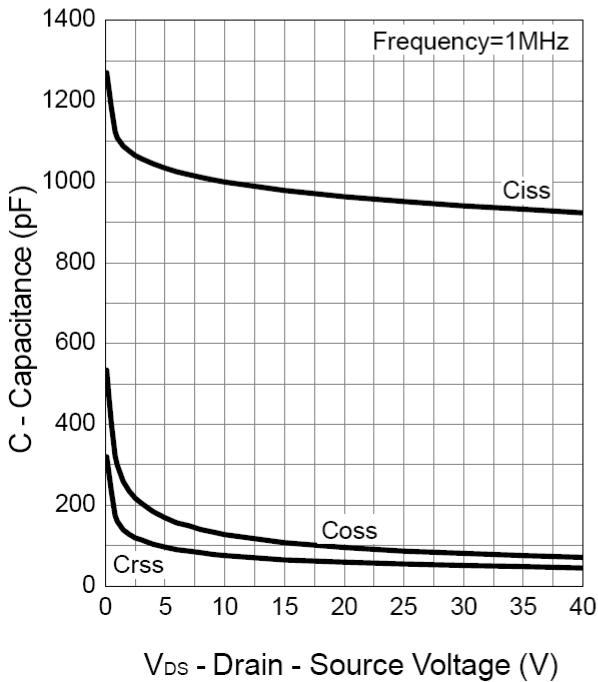
Drain-Source On Resistance



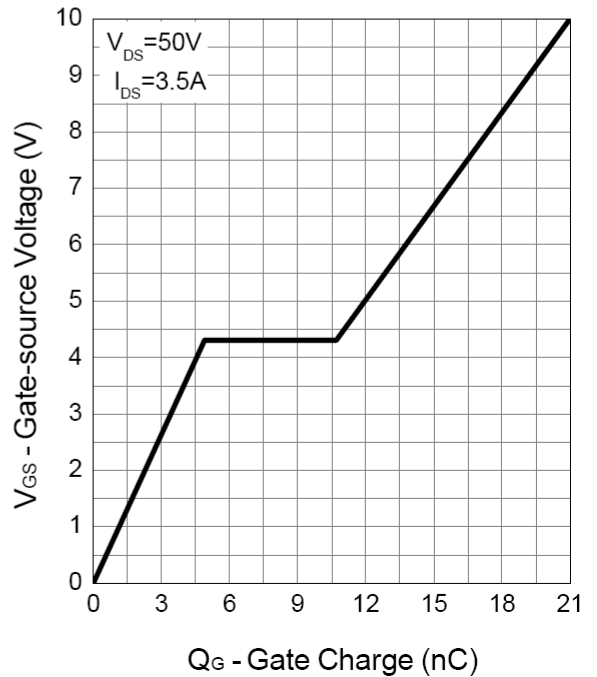
Source-Drain Diode Forward

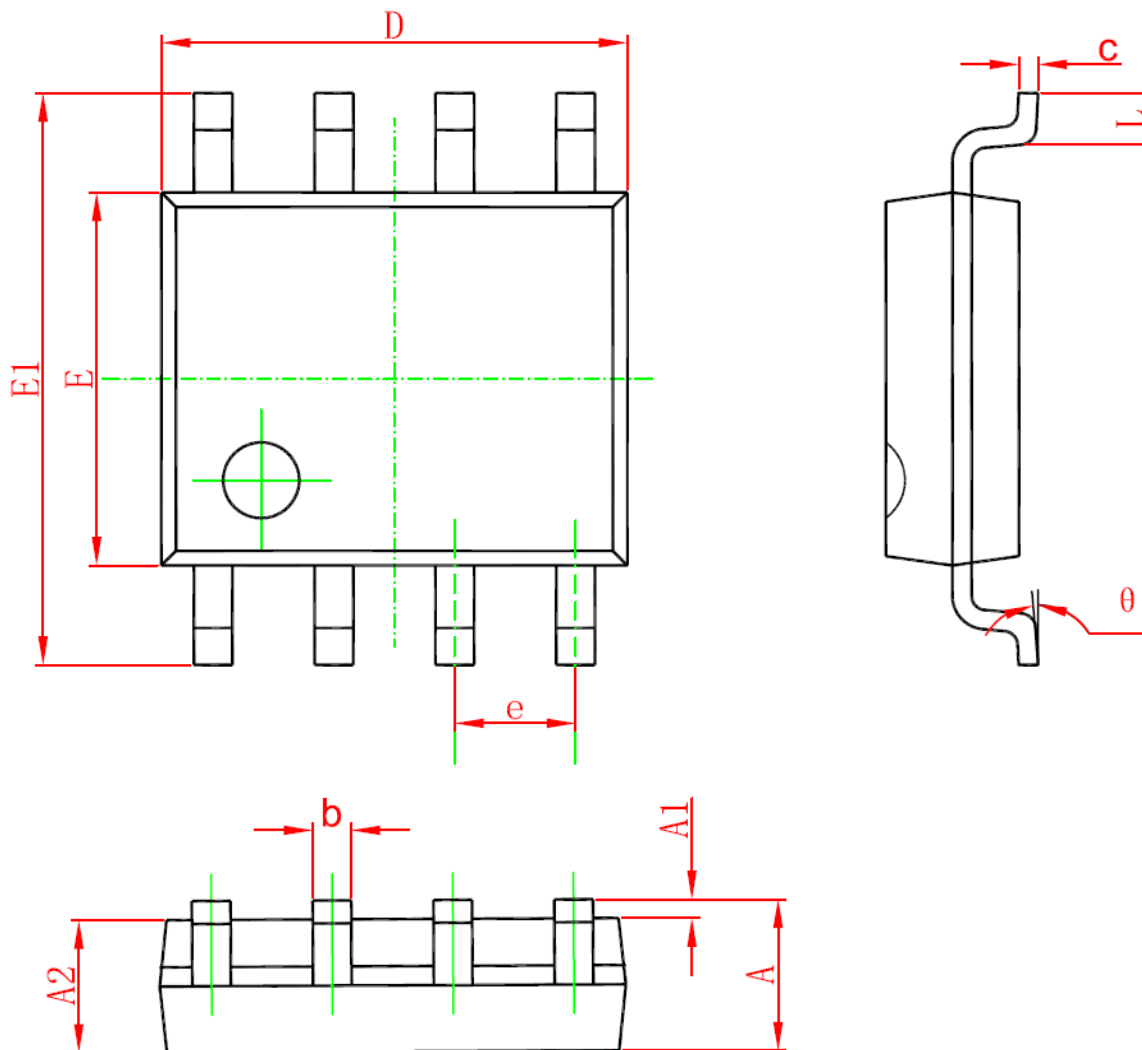


Capacitance



Gate Charge





Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

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